

# IEEE CPMT Switzerland Chapter

General Assembly  
September 30, 2013

at Sensirion AG  
Stäfa, Switzerland

# Agenda

- 16:00 Welcome address
- 16:05 Sensirion company presentation  
(Marc von Waldkirch)
- 16:50 Company tour (Werner Hunziker)
- 17:50 CPMT General Assembly
- 18:20 Apéro (offered by Sensirion AG)
- 19:15 Dinner at own expense at Restaurant Rössli  
(close to the Stäfa train station)

# Protocol of last GA on October 25, 2012

IEEE CPMT Switzerland Chapter



## Minutes of Administrative Chapter Meeting 2012 Including Chapter Board Elections

Date/Time: October 25, 2012, 16:00 hrs.  
Location: Microdul AG, Zurich

### Attendees

Hamit Duran (ABB, Chapter Chair)  
Didier Cottet (ABB, Vice Chair)  
Rony Jose James (CSEM, Program Officer and Webmaster)  
Zeno Stössel (HSLU, Treasurer)  
Kurt Mühleemann (Microdul)  
Stefan Weiss (Oclaro)  
Michael Schumacher (Enics)  
Werner Hunziker (Sensirion)  
Eduardo Jr. Baruelo (Semtech)  
Daniel Thommen (Microdul)  
Gernot Riedel (ABB)  
Slavo Kicin (ABB)

### Guests

Phil Poole (Microdul)  
Thomas Höchli (Enics)  
Samuel Hartmann (ABB)  
Roger Infanger (Microdul)

### Technical Part

A general introduction to Microdul was given by Daniel Thommen followed by a presentation of Roger Infanger on the development of a customized wafer prober with a highly precise temperature chuck. Finally, a lab tour was organized for all participants demonstrating the new clean room facilities at Microdul.

### Administrative Part

Chapter report presented by Hamit Duran

- Information about the chapter board and the membership status: 58
- Report about the 2011 activity of the CPMT Switzerland Chapter
  - Visit and general assembly at Oclaro Switzerland AG, Zurich on June 30, 2011
  - Joint seminar on optical packaging together with the Swiss Photonics and Laser Network (SLN) at CSEM in Alpnach Dorf on May 16, 2012 (see [www.ieee.ch/chapters/cpmt/events/optical-packaging-workshop/](http://www.ieee.ch/chapters/cpmt/events/optical-packaging-workshop/))
- Financial report (balance as of 31.12.2011): CHF 199.70
- Outlook 2013:
  - "Packaging reliability and failure analysis" was proposed by the chapter board as the focus topic for 2013. All attendees agreed.
  - INIEMI (<http://www.inemi.org/>) and the conference ISTFA (<http://www.asminternational.org/content/Events/istfa/>) were proposed as possible cooperation partners.

### Board elections

- Introduction by Hamit Duran.
- Two members of the board are stepping back:
  - Zeno Stössel, treasurer, co-founder and board member since 2000
  - Didier Cottet, vice chair, board member since 2006
- The work of the two leaving members was acknowledged.
- New candidates were:
  - Daniel Thommen, Microdul AG
  - Gernot Riedel, ABB Corporate Research
  - Slavomir Kicin, ABB Corporate Research
- All candidates presented themselves.
- A secret poll was carried out; each chapter member was allowed to vote for 2 candidates.
- Zeno Stössel and Didier Cottet were selected as vote counters.
- 11 ballots were valid, one was invalid. Voting result:
  - Daniel Thommen 10
  - Gernot Riedel 5
  - Slavomir Kicin 7
- Hence, Daniel Thommen and Slavomir Kicin were elected.
- The new chapter board will organize itself at a later stage.

### Social Part

An apéro was offered by Microdul AG after the administrative part. A common dinner in Zurich (at own expenses) concluded this event.

October 25, 2012

Hamit Duran  
Chapter Chair

# Chapter Summary

- CPMT chapter board (Since 2012)
  - Chapter chair: Hamit Duran (ABB)
  - Vice chair: Daniel Thommen (Microdul)
  - Treasurer: Rony Jose James (CSEM)
  - Program chair / webmaster: Slavo Kicin (ABB)
- Chapter size
  - 10. September 2012: 58 active members
  - 6. September 2013: 52 active members
  - Fluctuation: net 6 members leaving
- The board meets monthly via telco.
- Chapter information: [www.ieee.ch/chapters/cpmt/](http://www.ieee.ch/chapters/cpmt/)
- General overview on IEEE benefits: [ieee\\_benefits.ppt](#)

# Passed Program 2012/2013

- *October 25, 2012*  
Visit and **general assembly with board elections**  
at Microdul AG, Zurich
  - 14 participants
  - A general Microdul company presentation was given by Daniel Thommen
  - Roger Infanger presented a customized wafer prober with a highly precise temperature chuck
  - Afterwards, a company tour was organized for all participants
  - During the subsequent GA the new chapter board was elected
  - The event ended with an apéro offered by Microdul



# Passed Program 2012/2013



- *June 24, 2013*  
**Seminar on reliability of electronic components & systems**  
together with the Swiss Federal Laboratories for Materials Science and Technology (EMPA) in Dübendorf
  - 21 participants
  - 5 technical presentations:
    - “Reliability of large area solder joints: Numerical modeling and experimental results” (Dr. Gernot Riedel, ABB)
    - “Solder bump process optimization” (Dr. René Zingg, Melexis)
    - “Reliability of the cohesiveness of diverse connection technologies” (Jagoda Karlsson, Microdul)
    - “Design of accelerated tests for solder joints” (Günter Grossmann, EMPA)
    - “Denser scalable IC packages require jumps in technology and reliability” (Gerd Schlottig, IBM)
  - The technical part was followed by a lab tour and an Apéro offered by EMPA.

# Main IEEE CPMT Conferences in 2013

- Europe:
  - EMPC, European Microelectronics and Packaging Conference
  - Date: Sept. 9 – 12, 2013; Grenoble (F)
  - Web: <http://www.empc2013.com>
- USA:
  - ECTC, Electronics Component Technology Conference
  - Date: May 25 – June 2, 2013; Las Vegas
  - Web: <http://www.ectc.net>
- Asia:
  - EPTC, Electronics Packaging Technology Conference
  - Date: Dec. 11 – 13, 2013; Singapore
  - Web: <http://www.eptc-ieee.net>

# Financial Report

Balance 31.12.2011 CHF 199.70

## Expenses in 2012

- Gift for leaving board members CHF 100.00

## Income in 2012

- Interests on bank account CHF 0.45

Balance 31.12.2012 CHF 100.15

19.09.2013  
Rony Jose James  
Treasurer



## Financial Outlook for 2013

- We received a funding of CHF 500.- for 2013.
- The IEEE Switzerland Section decided on its ExCom meeting of Sept. 5, 2013 that from now on each chapter shall get a funding of CHF 500.- per year without the need for a special approval.

# Outlook 2014

- Possible topics for seminars/talks in 2014
  - 3D packaging
  - Biomedical packaging
  - Microwave/RF packaging
  - Wild card - New trends in packaging
- Joint event with IEEE CPMT chapter in neighboring countries (Germany, Austria, France, Italy)?

# Comments / Questions?

# 19:15 Dinner at Restaurant “Rössli”

- **Address:**  
Bahnhofstr. 1  
8712 Stäfa

